

AMENDMENTS TO THE CLAIMS

Listing of the claims:

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

1. (Currently Amended) A component of a film-forming device in which a thin film is formed on a substrate using a film-forming material, the component of the film-forming device comprising: ~~being characterized in that~~

a body having a back face and a top face and a large number of through holes each extending from the back face to the top face of the component are formed therein,
wherein one of the back face and the top face includes a surface on which the thin film is adhered during use, and the through holes provide access from the other one of the back face and the top face to the thin film adhered on the surface, whereby for the penetration of a cleaning solution is permitted to penetrate into a the boundary between the surface and the thin film adhered thereon component and a film of the film-forming material adhered to the surface of the component and formed during the formation of the foregoing thin film.

2. (Currently Amended) The component of a film-forming device according to claim 1, ~~[[.]]~~ wherein the through holes have a diameter smaller than a size of any particle of the film-forming material or a plasma thereof, thereby preventing of the component is so designed that they have a diameter, which can inhibit the penetration of any particle of the film-forming material or the plasma thereof into the through holes.

3. (Currently Amended) The component of a film-forming device according to claim 1 or 2, wherein the through holes are formed in such a manner that they are not

perpendicular vertical to the surface of the body of the component, ~~but are tilted towards~~
~~the horizontal direction.~~

4. (Currently Amended) The component of a film-forming device according to claim 1, further comprising wherein a layer consisting of a metal film that is easily soluble in the cleaning solution ~~is formed~~ provided on the surface thereof prior to adherence of the thin film thereon during use ~~of the component according to a method~~ ~~such as thermal spraying, vapor deposition, sputtering, plating and lamination~~ ~~techniques.~~

5. (Currently Amended) A method for cleaning a component of a film-forming device comprising the steps ~~step~~ of:

preparing a body of the component with through holes that extend therethrough;
and

immersing[[,]] the body of the component into a cleaning solution to remove a film
adhered to a surface of the body during use, whereby the cleaning solution enters into
the through holes and penetrates a boundary between the surface of the body and the
film adhered thereto ~~a component as set forth in claim 1 for the removal of a film~~
~~adhered to the component.~~

6. (Currently Amended) The [[A]] method for cleaning a component of a film-
forming device according to claim 5, wherein comprising the step of preparing the body
with the through holes includes forming the through holes to be at an angle to the
surface other than 90° ~~immersing, into a cleaning solution, a component as set forth in~~
~~claim 2 for the removal of a film adhered to the component.~~

7. (Currently Amended) The [[A]] method for cleaning a component of a film-forming device according to claim 5, wherein comprising the step of preparing the body with the through holes includes forming the through holes to have a diameter smaller than a size of any particle of film-forming material used in the film-forming device
~~immersing, into a cleaning solution, a component as set forth in claim 3 for the removal of a film adhered to the component.~~

8. (Currently Amended) The [[A]] method for cleaning a component of a film-forming device according to claim 5, further comprising the step of forming a layer consisting of a metal film easily soluble in the cleaning solution on the surface of the body prior to the adherence of the film thereon during use
~~of the component according to a method such as thermal spraying, vapor deposition, sputtering, plating and lamination techniques.~~

9. (New) A component for use in a film-forming device in which a thin film is formed on a substrate using a film-forming material, the component of the film-forming device comprising:

means for affecting formation of the thin film on the substrate, the means for affecting formation of the thin film having a surface on which the thin film is also formed during use;

means for allowing penetration of a cleaning solution used to remove the thin film from the surface of the means for affecting formation of the thin film into a boundary between the surface of the means for affecting formation of the thin film and the thin film formed thereon.

10. (New) The component for use in a film-forming device according to claim 9, wherein the means for affecting formation of the thin film comprises a body having a back face and a top face and the means for allowing penetration of a cleaning solution includes a plurality of through holes each extending from the back face to the top face of the body.

11. (New) The component for use in a film-forming device according to claim 10, wherein the through holes have a diameter that inhibits penetration of any particle of the film-forming material or a plasma thereof into the through holes.

12. (New) The component for use in a film-forming device according to claim 10 or 11, wherein the through holes are formed at an acute angle to the surface of the means for affecting formation of the thin film.

13. (New) The component for use in a film-forming device according to claim 9, further comprising a layer formed on the surface of the means for affecting formation of the thin film before the thin film is formed thereon during use, the layer consisting of a metal film easily soluble in the cleaning solution used to remove the thin film from the means for affecting formation of the thin film.

14. (New) The method for cleaning a component of a film-forming device according to claim 8, wherein the step of forming the layer includes forming the layer on the surface of the body by one selected from the group consisting of thermal spraying, vapor deposition, sputtering, plating, lamination and any combination thereof.